Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	100	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current (Note 5) V_{GS} = 10V	Steady State	T_C = +25°C T_C = +100°C	I_D	12 7.5	A
Maximum Body Diode Forward Current (Note 5)			I_S	4	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I_{DM}	16	A
Avalanche Current (Note 6)			I_{AS}	5.3	A
Avalanche Energy (Note 6)			E_{AS}	20	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_C = +25°C	P_D	42	W
	T_C = +100°C		17	
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	44	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	3	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 100V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	2.0	3.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	99	140	mΩ	V_{GS} = 10V, I_D = 5A
		—	104	160		V_{GS} = 4.5V, I_D = 5A
Diode Forward Voltage	V_{SD}	—	0.7	1.0	V	V_{GS} = 0V, I_S = 10A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1,167	—	pF	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	36	—		
Reverse Transfer Capacitance	C_{rss}	—	25	—		
Gate Resistance	R_G	—	1.3	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	4.9	—	nC	V_{DS} = 80V, I_D = 12.8A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	9.7	—		
Gate-Source Charge	Q_{gs}	—	2.0	—		
Gate-Drain Charge	Q_{gd}	—	2.0	—		
Turn-On Delay Time	$t_{D(on)}$	—	10.5	—	nS	V_{DD} = 50V, R_G = 25Ω, I_D = 12.8A
Turn-On Rise Time	t_r	—	11.1	—		
Turn-Off Delay Time	$t_{D(off)}$	—	42.6	—		
Turn-Off Fall Time	t_f	—	12.8	—		
Body Diode Reverse Recovery Time	t_{rr}	—	30.3	—	nS	V_{GS} = 0V, I_S = 12.8A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{rr}	—	35.2	—	nC	V_{GS} = 0V, I_S = 12.8A, dI/dt = 100A/µs

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper pad layout.
6. UIS in production with L = 1.43mH, T_J = +25°C.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design; not subject to production testing.

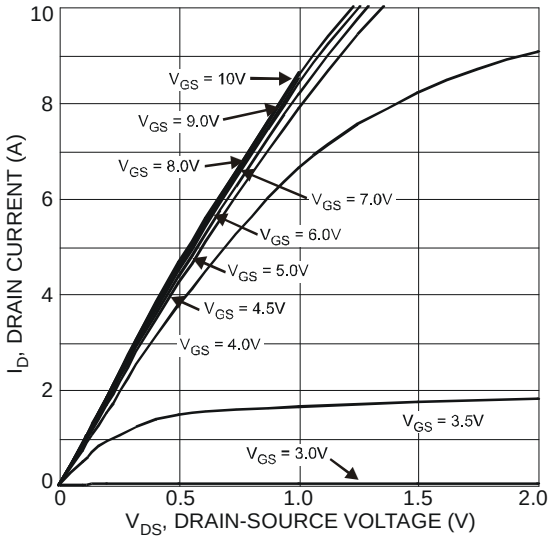


Fig.1 Typical Output Characteristic

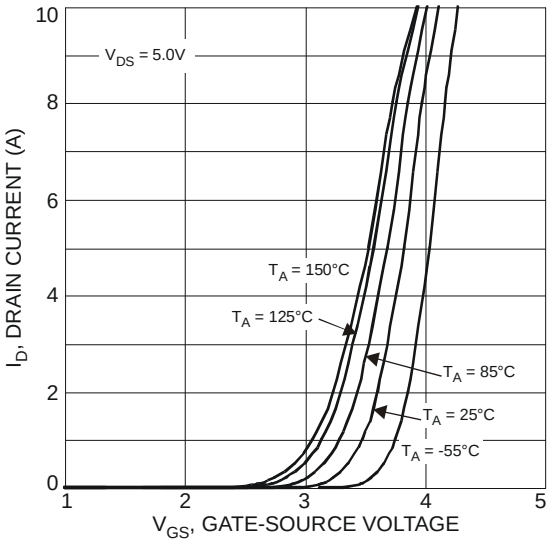


Fig.2 Typical Transfer Characteristics

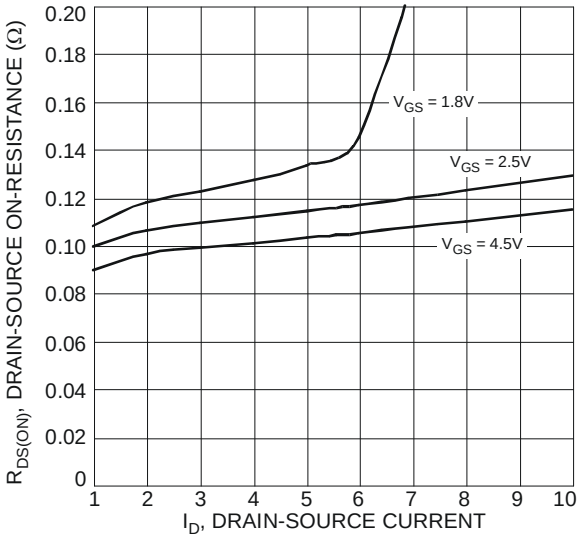


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

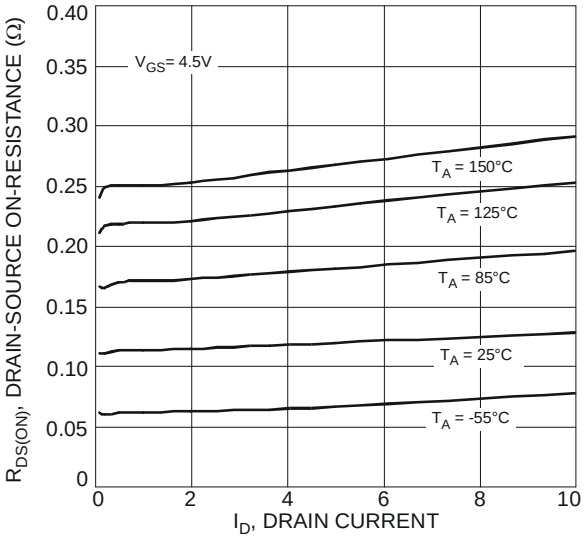


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

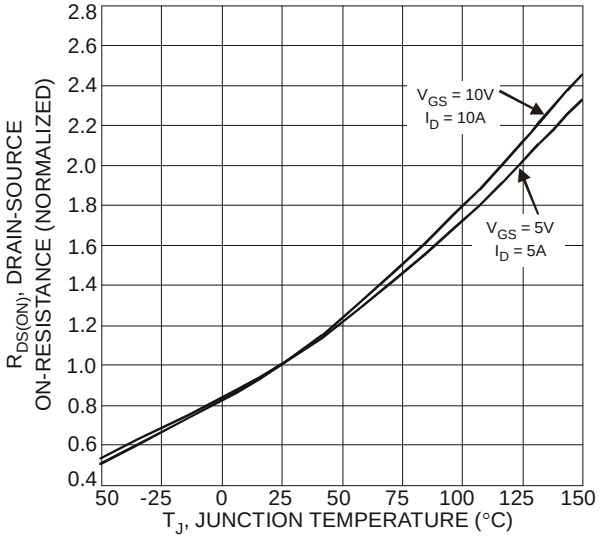


Fig. 5 On-Resistance Variation with Temperature

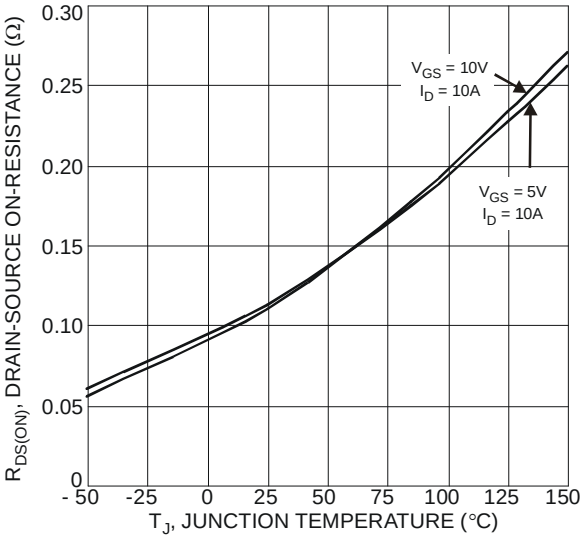


Fig. 6 On-Resistance Variation with Temperature

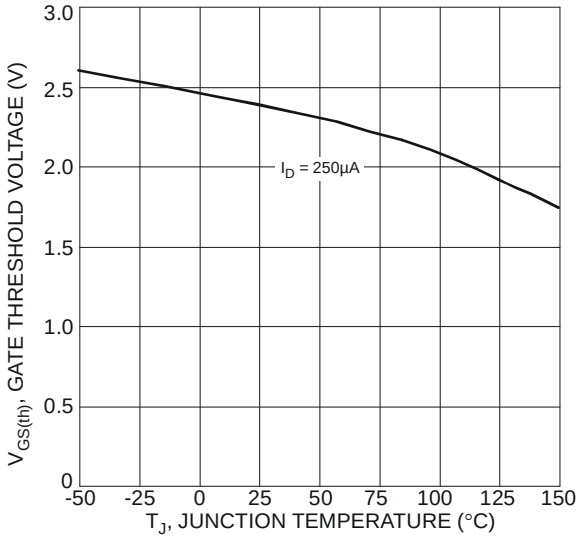


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

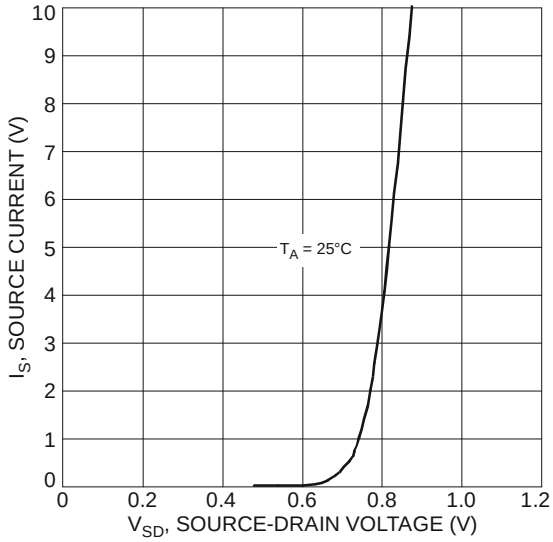


Fig.8 Diode Forward Voltage vs. Current

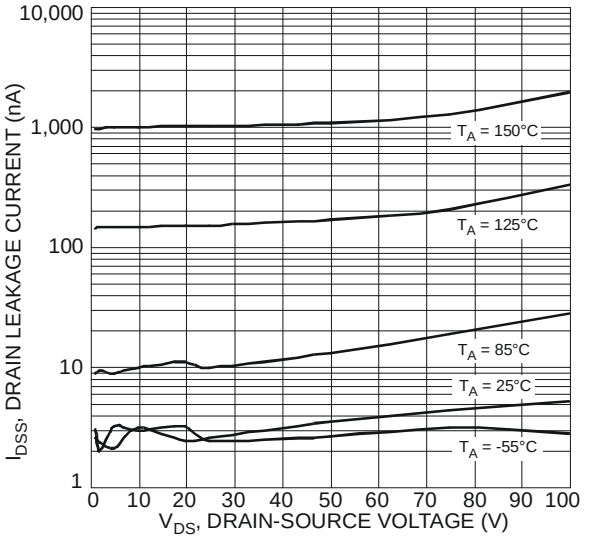


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage

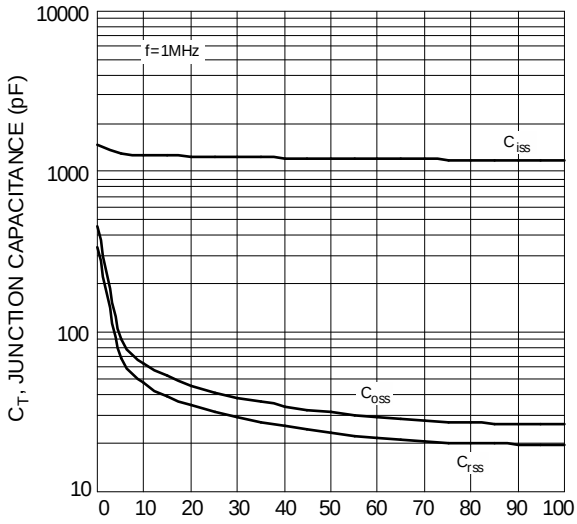


Figure 10 Typical Junction Capacitance

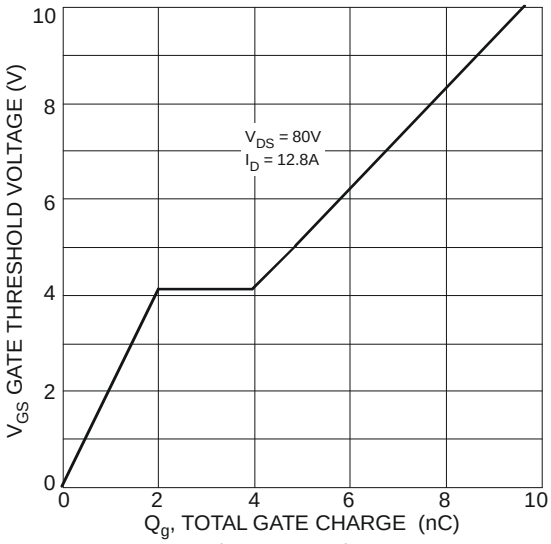


Fig. 11 Gate Charge

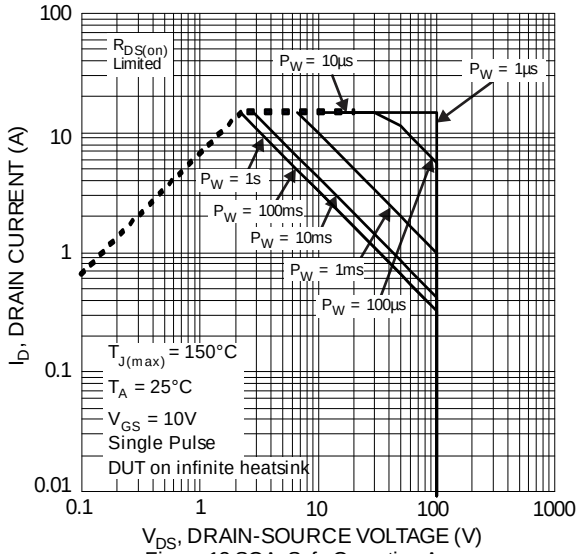


Figure 12 SOA, Safe Operation Area

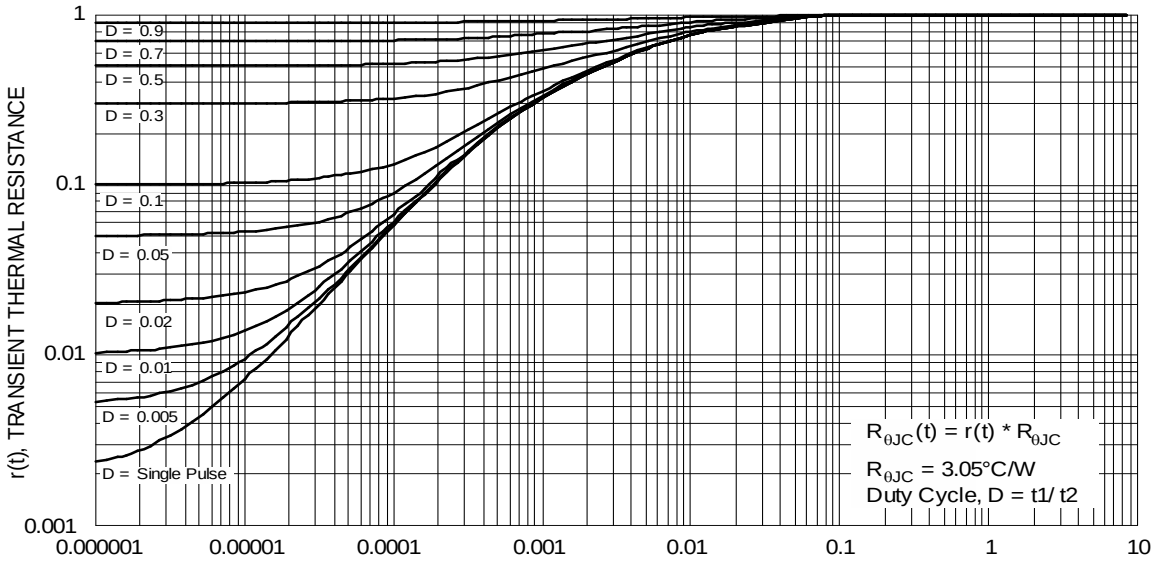
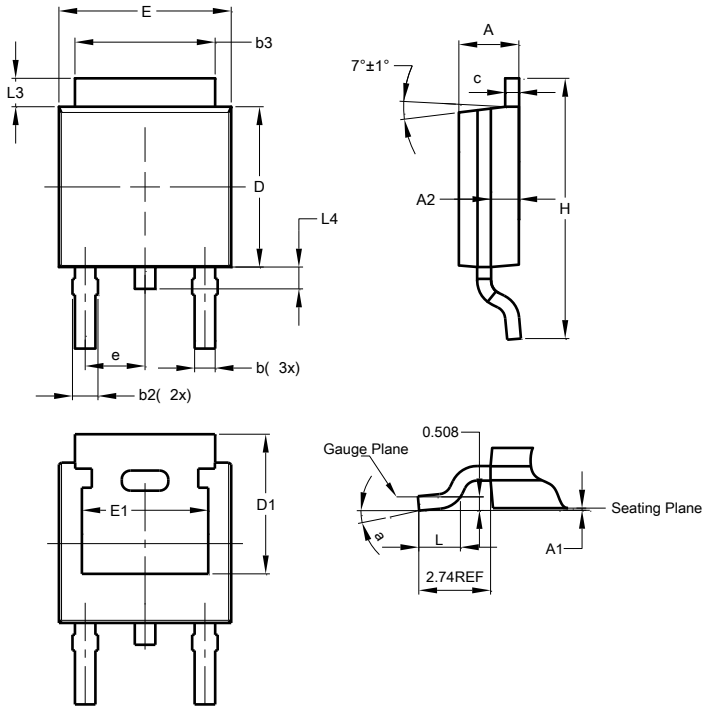


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

TO252 (DPAK)

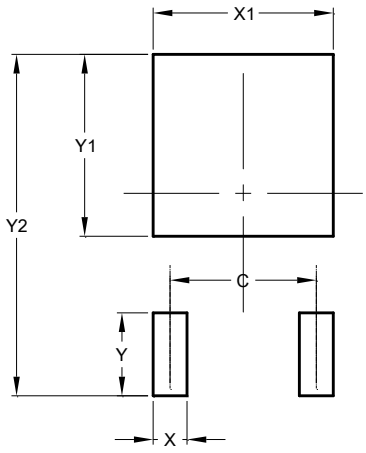


TO252 (DPAK)			
Dim	**Min**	**Max**	**Typ**
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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